

FORM PTO-1449 (Modified)

ATTY. DOCKET NO.

SERIAL NO.

END920020027US1

10/ 806 806

LIST OF PATENTS AND PUBLICATIONS FOR  
APPLICANT'S INFORMATION  
DISCLOSURE STATEMENTAPPLICANT: CLÉMENT J.  
FORTIN, ET AL.

PAGE 1 OF 1

(Use several sheets if necessary)

FILING DATE:

GROUP: 2813

## Reference

## US Patent Documents

## Designation

EXAMINER INITIALS		DOCUMENT NUMBER	ISSUE DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPRO.)
<i>QMD</i>	AA	4,339,785	07/13/82	OHSAWA	361	411	04/08/80
<i>QMD</i>	AB	5,085,364	02/04/92	ISHIKAWA, ET AL.	228	139	09/05/90
<i>QMD</i>	AC	5,128,746	07/07/92	PENNISI, ET AL.	357	72	09/27/90
<i>QMD</i>	AD	5,493,259	02/20/96	BLALOCK, ET AL.	333	182	03/06/95
<i>QMD</i>	AE	5,529,957	07/25/96	CHAN	437	250	04/06/95
<i>QMD</i>	AF	5,814,401	09/29/98	GAMOTA, ET AL.	428	343	02/04/97
<i>QMD</i>	AG	6,071,371	06/06/00	LEONARD, ET AL.	156	297	02/02/98
<i>QMD</i>	AH	6,202,917B1	03/20/01	WEAVER, ET AL.	228	180	08/19/98
	AI						
	AJ						
	AK						

Foreign Patent  
Documents

<i>QMD</i>	AL	JP401100993A	04/19/89	AKIYAMA	H05K3	34	10/14/87
	AM						
	AN						
	AO						

OTHER ART (Including  
Author, Title, Date,  
Pertinent Pages, etc.)*QMD* AP AMICON® E 1350 Series, "No Flow-Fluxing Underfill Encapsulants for Flip Chip Devices",  
Emerson & Cuming, Specialty Polymers.*QMD* AQ SE-CURE® 9101 "Reflow Encapsulant", Kester Solder, Polymer Products Group.*QMD* AR STAYCHIP™, NUF-DP0071 - No Flow Underfill, Developmental Product Information.*QMD* AS DEXTER, HYSOL® FF 2200, "Reflow Encapsulant".*QMD* AT DEXTER, HYSOL® FluxFill™ 2000, "Reflow Encapsulant".

EXAMINER

DATE CONSIDERED

6/9/05

EXAMINER: Initial if reference considered,  
whether or not citation is in conformance  
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